

**Amendments to the Claims:**

Please cancel claims 5-8 and amend claims 1-4 as follows.  
The following listing of claims will replace all prior versions,  
and listings, of claims in the application:

**Listing of Claims:**

Claim 1 (Currently Amended). A wafer holding device for use  
in an apparatus for treating a principal surface of a  
semiconductor wafer under a predetermined heating condition while  
the back surface of said principal surface of the wafer is held  
by the device at a predetermined position within a chamber of  
said apparatus, said device comprising:

a susceptor formed in the surface thereof with a wafer  
loading area for supporting the back surface of the wafer,

a plurality of support pins each arranged at one of four  
equiangularly spaced positions along a circumference of at least  
one concentric circle in said wafer loading area so as to  
protrude from the surface of said susceptor, and

a resilient mechanism made from ~~at least one of quartz of~~  
~~SiC~~ for supporting said support pins.

Claim 2 (Currently Amended). The wafer holding device according to claim 1, wherein said support pins are disposed in position which support the wafer along the crystal orientation ~~(110)~~ with respect to the crystal plane ~~(100)~~ of the wafer.

Claim 3 (Currently Amended). The wafer holding device according to claim 1, wherein said resilient mechanism includes a plurality of flexible members made from ~~at least one of quartz or SiC~~ each supporting one of said support pins.

Claim 4 (Currently Amended). A wafer holding device adapted for use in an apparatus for treating a principal surface of a semiconductor wafer under a predetermined heating condition while the back surface of said principal surface of the wafer is held by the device at a predetermined position within a chamber of said apparatus, said device comprising:

a susceptor formed in the surface thereof with a wafer loading area of supporting the back surface of the wafer, and

a plurality of support pins each arranged at one of four equiangularly spaced positions along a circumference of at least one concentric circle in said wafer loading area so as to protrude from the surface of said susceptor, each of said support

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pins including a resilient mechanism, wherein said resilient mechanism includes a plurality of flexible members each supporting one of said support pins,

wherein each said flexible member comprises a leaf spring made from ~~at least one of quartz or SiC~~.

Claims 5-8 (Cancelled).